

Chip Bead For EMI Suppression

CIS10P Series (1608 / EIA 0603)

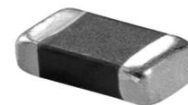
APPLICATION

Noise Suppression in power line

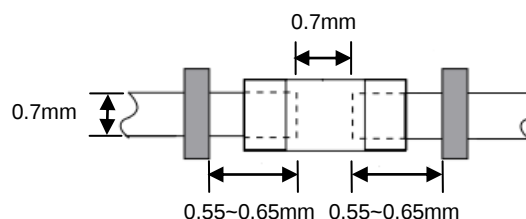
FEATURES

Smallest beads used in high current.

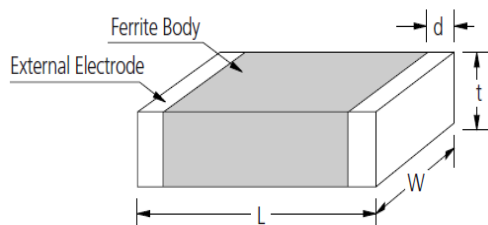
- CIS series is used for high current.



RECOMMENDED LAND PATTERN



DIMENSION

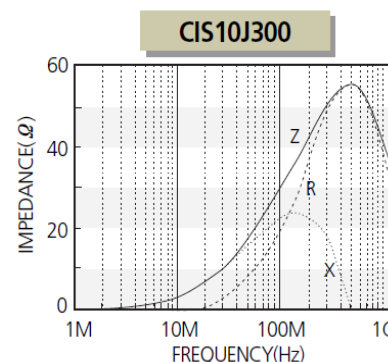
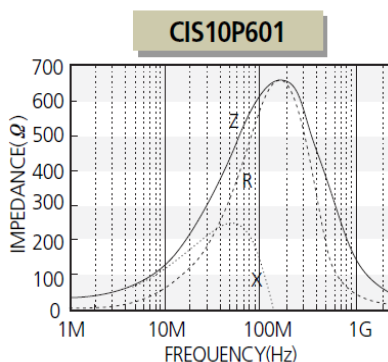
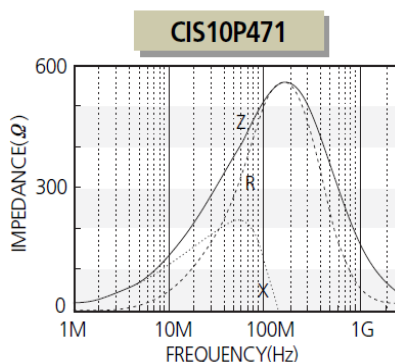
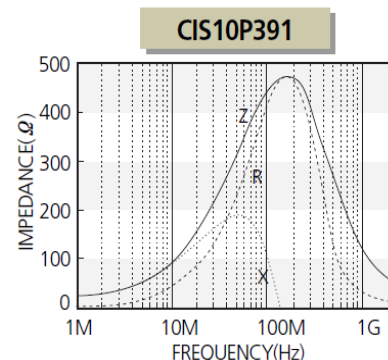
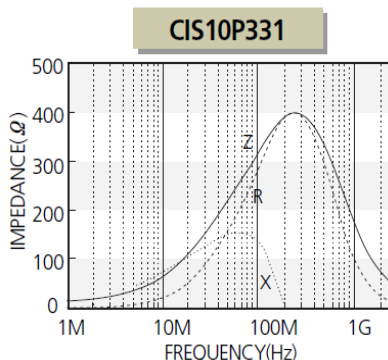
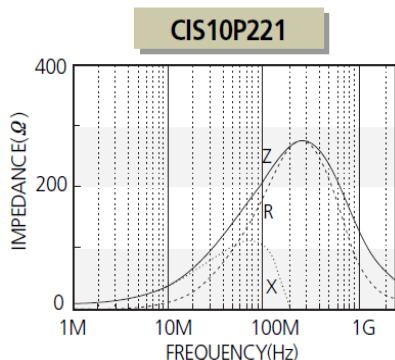
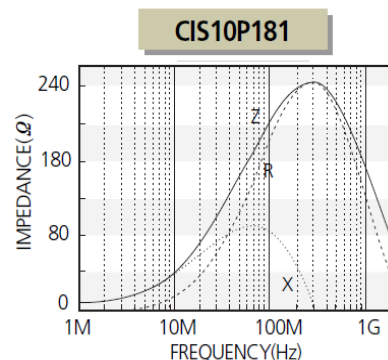
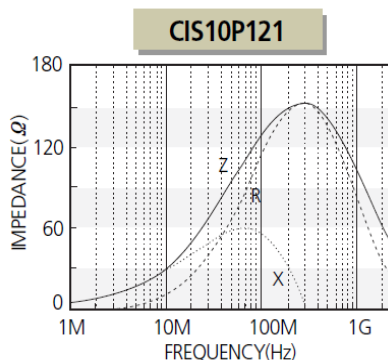
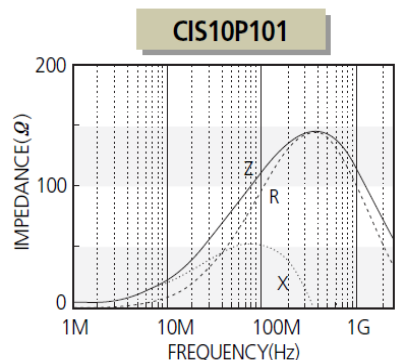
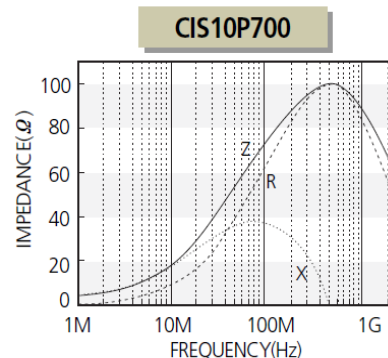
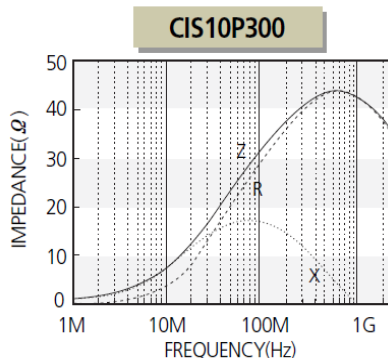
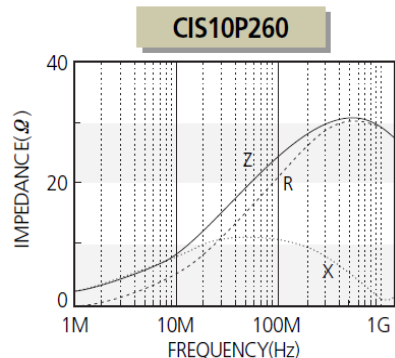


Type	Dimension [mm]			
	L	W	t	d
10	1.6±0.15	0.8±0.15	0.8±0.15	0.3±0.2

DESCRIPTION

Part No.	Thickness (mm)	Impedance (Ω) ±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIS10P260AC	0.6±0.15	26	0.007	6000
CIS10P300AC	0.6±0.15	30	0.01	6000
CIS10P700AC	0.6±0.15	70	0.02	4000
CIS10P101AC	0.6±0.15	100	0.03	3000
CIS10P121AC	0.6±0.15	120	0.03	3000
CIS10P181AC	0.6±0.15	180	0.04	2500
CIS10P221NC	0.8±0.15	220	0.05	2500
CIS10P301NC	0.8±0.15	300	0.07	2000
CIS10P331NC	0.8±0.15	330	0.07	1700
CIS10P391NC	0.8±0.15	390	0.10	1200
CIS10P471NC	0.8±0.15	470	0.13	1500
CIS10P601NC	0.8±0.15	600	0.15	1300
CIS10J300NC	0.8±0.15	30	0.01	6000

CHARACTERISTIC DATA



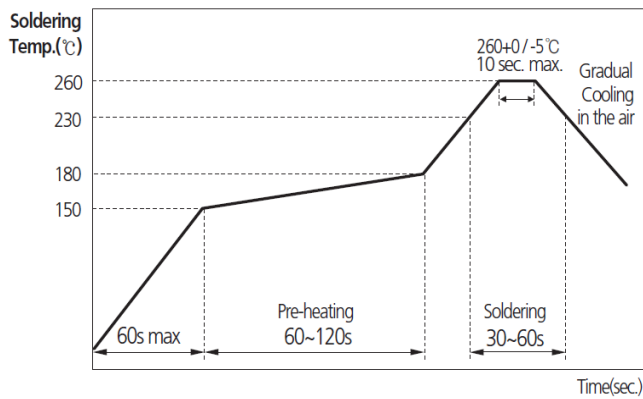
PRODUCT IDENTIFICATION

CI S 10 P 260 A C
(1) (2) (3) (4) (5) (6) (7)

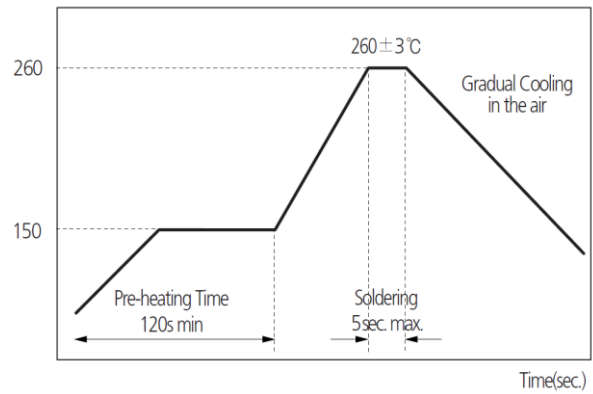
- (1) Chip Beads (2) Ultra high current
(3) Dimension (4) Material Code
(5) Nominal impedance (260: 26Ω , 300:30Ω , 121:120Ω)
(6) Thickness option (N:Standard, A:Thinner than standard, B:Thicker than standard)
(7) Packaging (C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Type	Quantity (pcs/reel)
Card Board Taping	4000



Any data in this sheet are subject to change, modify or discontinue without notice.

The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.